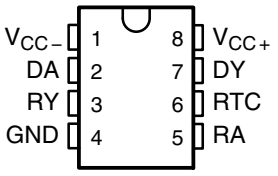
SLLS017C – JULY 1986 – REVISED MAY 1995

- **Meets or Exceeds the Requirements of ANSI EIA/TIA-232-E and ITU Recommendation V.28**
- **10-mA Current Limited Output**
- **Wide Range of Supply Voltage**
  V_{CC} = 4.5 V to 15 V
- **Low Power . . . 130 mW**
- **Built-In 5-V Regulator**
- **Response Control Provides:**
  Input Threshold Shifting
  Input Noise Filtering
- **Power-Off Output Resistance . . . 300 Ω Typ**
- **Driver Input TTL Compatible**

D OR P PACKAGE
TOP VIEW

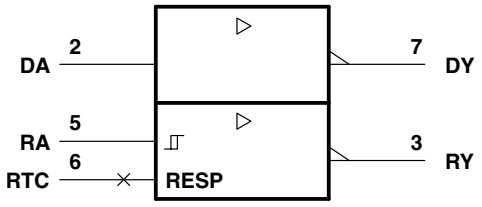


description

The SN75155 monolithic line driver and receiver is designed to satisfy the requirements of the standard interface between data terminal equipment and data communication equipment as defined by ANSI EIA/TIA-232-E. A response control input is provided for the receiver. A resistor or a resistor and a bias voltage can be connected between the response control input and ground to provide noise filtering. The driver used is similar to the SN75188. The receiver used is similar to the SN75189A.

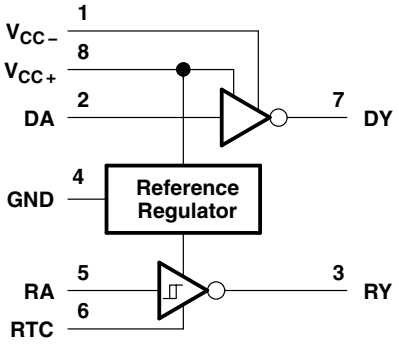
The SN75155 is characterized for operation from 0°C to 70°C.

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12

logic diagram

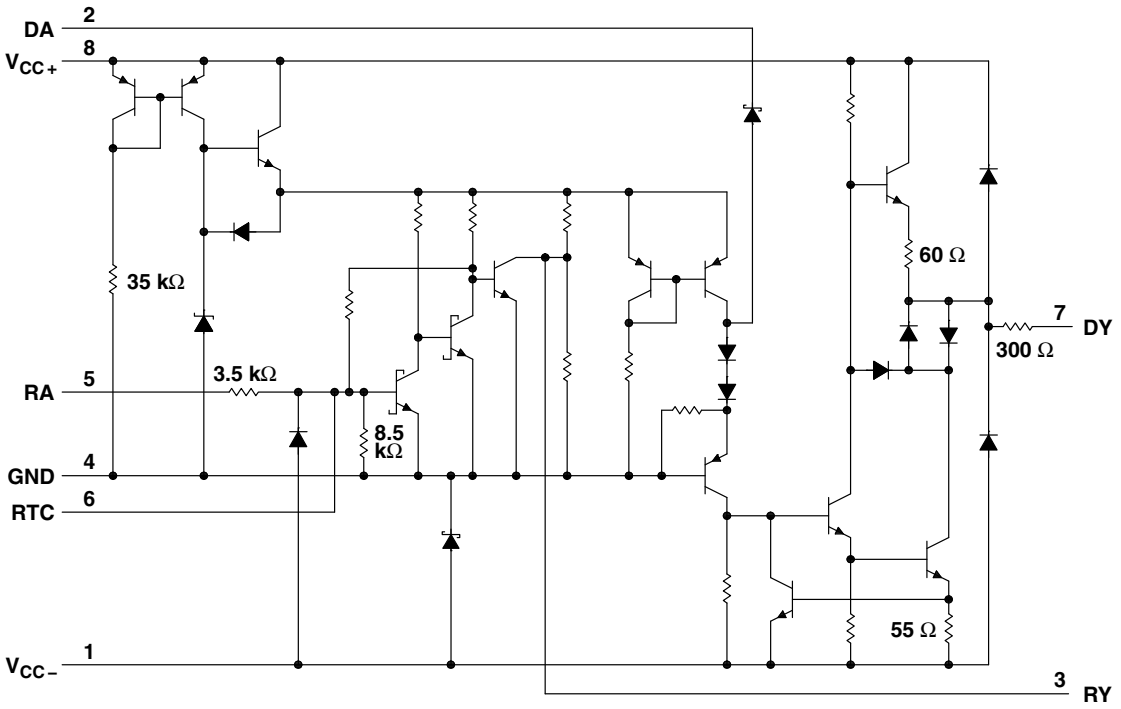


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

Copyright © 1995, Texas Instruments Incorporated

schematic



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC+} (see Note 1) . . . . . 15 V
Supply voltage, V_{CC-} (see Note 1) . . . . . –15 V
Input voltage range, V_I: Driver . . . . . –15 V to 15 V
Receiver . . . . . –30 V to 30 V
Output voltage range (driver), V_O . . . . . –15 V to 15 V
Continuous total power dissipation . . . . . See Dissipation Rating Table
Operating free-air temperature range, T_A . . . . . 0°C to 70°C
Storage temperature range, T_{stg} . . . . . –65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds . . . . . 260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to network ground terminal.

DISSIPATION RATING TABLE

PACKAGE	$T_A \le 25°C$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25°C$	$T_A = 70°C$ POWER RATING
D	725 mW	5.8 mW/°C	464 mW
P	1000 mW	8.0 mW/°C	640 mW

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V_{CC+}	4.5	12	15	V
Supply voltage, V_{CC-}	−4.5	−12	−15	V
Output voltage, driver, $V_{O(D)}$			±15	V
Input voltage, receiver, $V_{I(R)}$	−25		25	V
High-level input voltage, driver, V_{IH}	2			V
Low-level input voltage, driver, V_{IL}			0.8	V
Response control current			±5.5	mA
Output current, receiver, $I_{O(R)}$			24	mA
Operating free-air temperature, T_A	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

total device

PARAMETER		TEST CONDITIONS			MIN	TYP†	MAX	UNIT
I_{CCH+}	High-level supply current	V_{CC+} = 5 V,	V_{CC-} = −5 V	$V_{I(D)}$ = 2 V, $V_{I(R)}$ = 2.3 V, Output open		6.3	8.1	mA
		V_{CC+} = 9 V,	V_{CC-} = −9 V			9.1	11.9	
		V_{CC+} = 12 V,	V_{CC-} = −12 V			10.4	14	
I_{CCL+}	Low-level supply current	V_{CC+} = 5 V,	V_{CC-} = −5 V	$V_{I(D)}$ = 0.8 V, $V_{I(R)}$ = 0.6 V, Output open		2.5	3.4	mA
		V_{CC+} = 9 V,	V_{CC-} = −9 V			3.7	5.1	
		V_{CC+} = 12V,	V_{CC-} = −12 V			4.1	5.6	
I_{CC+}	Supply current	V_{CC+} = 5 V,	V_{CC-} = 0	$V_{I(R)}$ = 2.3 V, $V_{I(D)}$ = 0		4.8	6.4	mA
		V_{CC+} = 9 V,	V_{CC-} = 0			6.7	9.1	
I_{CCH-}	High-level supply current	V_{CC+} = 5 V,	V_{CC-} = −5 V	$V_{I(D)}$ = 2 V, $V_{I(R)}$ = 2.3 V Output open		−2.4	−3.1	mA
		V_{CC+} = 9 V,	V_{CC-} = −9 V			−3.9	−4.9	
		V_{CC+} = 12 V,	V_{CC-} = −12 V			−4.8	−6.1	
I_{CCL-}	Low-level supply current	V_{CC+} = 5 V,	V_{CC-} = −5 V	$V_{I(D)}$ = 0.8 V, $V_{I(R)}$ = 0.6 V, Output open		−0.2	−0.35	mA
		V_{CC+} = 9 V,	V_{CC-} = −9 V			−0.25	−0.4	
		V_{CC+} = 12 V,	V_{CC-} = −12 V			−0.27	−0.45	

† All typical values are at T_A = 25°C.

electrical characteristics over recommended operating free-air temperature range, V_{CC+} = 12 V, V_{CC-} = −12 V (unless otherwise noted)

driver section

PARAMETER		TEST CONDITIONS			MIN	TYP†	MAX	UNIT
V_{OH}	High-level output voltage	V_{IL} = 0.8 V, R_L = 3 kΩ	V_{CC+} = 5 V,	V_{CC-} = −5 V	3.2	3.7		V
			V_{CC+} = 9 V,	V_{CC-} = −9 V	6.5	7.2		
			V_{CC+} = 12 V,	V_{CC-} = −12 V	8.9	9.8		
V_{OL}	Low-level output voltage (see Note 2)	V_{IH} = 2 V, R_L = 3 kΩ	V_{CC+} = 5 V,	V_{CC-} = −5 V		−3.6	−3.2	V
			V_{CC+} = 9 V,	V_{CC-} = −9 V		−7.1	−6.4	
			V_{CC+} = 12 V,	V_{CC-} = −12 V		−9.7	−8.8	
I_{IH}	High-level input current	V_I = 7 V					5	μA
I_{IL}	Low-level input current	V_I = 0				−0.73	−1.2	mA
$I_{OS(H)}$	High-level short-circuit output current	V_I = 0.8 V, V_O = 0			−7	−12	−14.5	mA
$I_{OS(L)}$	Low-level short-circuit output current	V_I = 2 V, V_O = 0			6.5	11.5	15	mA
r_O	Output resistance with power off	V_O = −2 V to 2 V				300		Ω

receiver section (see Figure 1)

PARAMETER		TEST CONDITIONS			MIN	TYP†	MAX	UNIT
V_{IT+}	Positive-going input threshhold voltage				1.2	1.9	2.3	V
V_{IT-}	Negative-going input threshhold voltage				0.6	0.95	1.2	V
V_{hys}	Hystresis voltage ($V_{IT+} - V_{IT-}$)				0.6			V
$V_{O(H)}$	High-level output voltage	V_I = 0.6 V, I_{OH} = 10 μA	V_{CC+} = 5 V,	V_{CC-} = −5 V	3.7	4.1	4.5	V
			V_{CC+} = 12 V,	V_{CC-} = −12 V	4.4	4.7	5.2	
		V_I = 0.6 V, I_{OH} = 0.4 mA	V_{CC+} = 5 V,	V_{CC-} = −5 V	3.1	3.4	3.8	
			V_{CC+} = 12 V,	V_{CC-} = −12 V	3.6	4	4.5	
$V_{O(L)}$	Low-level output voltage	V_I = 2.3 V,	I_{OL} = 24 mA			0.2	0.3	V
I_{IH}	High-level input current	V_I = 2 5 V			3.6	6.7	10	mA
		V_I = 3 V			0.43	0.67	1	mA
I_{IL}	Low-level input current	V_I = −25 V			−3.6	−6.7	−10	mA
		V_I = −3 V			−0.43	−0.67	−1	mA
I_{OS}	Short-circuit output current	V_I = 0.6 V				−2.8	−3.7	mA

† All typical values are at T_A = 25°C.

NOTE 2: The algebraic limit system, in which the more positive (less negative) limit is designated as maximum, is used in this data sheet for logic voltage levels only (e.g., if −8.8 V is the maximum, the typical value is a more negative value).

switching characteristics over recommended operating free-air temperature range, V_{CC+} = 5 V, V_{CC-} = – 5 V, C_L = 50 pF (unless otherwise noted)

driver section (see Figure 2)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
t_{PLH}	Propagation delay time, low- to high level output	R_L = 3 kΩ		250	480	ns
t_{PHL}	Propagation delay time, high- to low level output			80	150	
t_r	Output rise time	R_L = 3 kΩ		67	180	ns
		R_L = 3 kΩ to 7 kΩ, C_L = 2500 pF		2.4	3	µs
t_f	Output fall time	R_L = 3 kΩ		48	160	ns
		R_L = 3 kΩ to 7 kΩ, C_L = 2500 pF		1.9	3	µs

receiver section (see Figure 3)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
t_{PLH}	Propagation delay time, low- to high level output	R_L = 400 Ω		175	245	ns
t_{PHL}	Propagation delay time, high- to low level output			37	100	
t_r	Output rise time	R_L = 400 Ω		255	360	ns
t_f	Output fall time	R_L = 400 Ω		23	50	ns

† All typical values are at T_A = 25°C.

PARAMETER MEASUREMENT INFORMATION

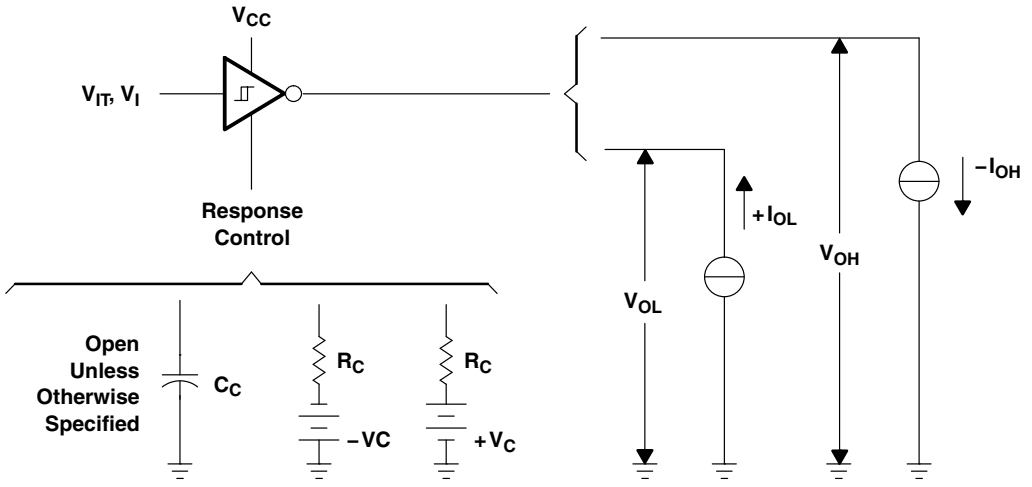
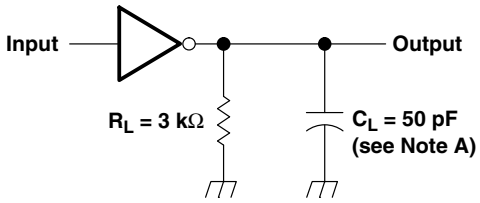
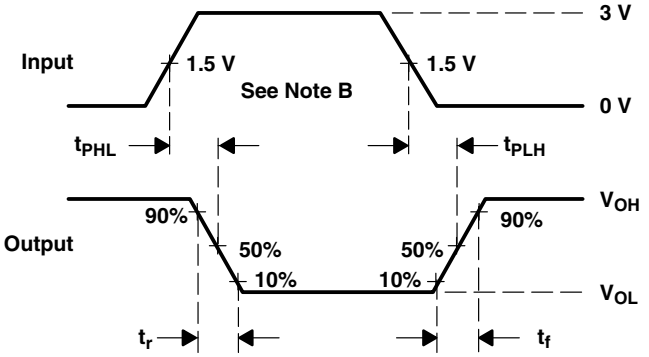


Figure 1. Receiver Section Test Circuit (V_{IT+}, V_{IT-}, V_{OH}, V_{OL})

PARAMETER MEASUREMENT INFORMATION



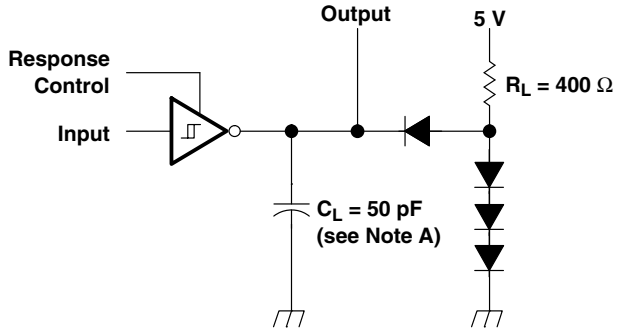
TEST CIRCUIT



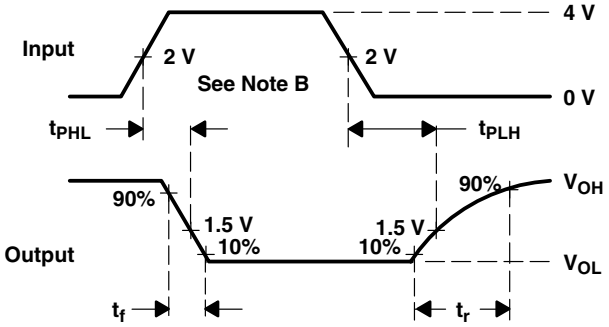
VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. The input waveform is supplied by a generator with the following characteristics: Z_O = 50 Ω, t_w = 1 μs, $t_r \le 10$ ns, $t_f \le 10$ ns.

Figure 2. Driver Section Switching Test Circuit and Voltage Waveforms



TEST CIRCUIT



VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. The input waveform is supplied by a generator with the following characteristics: Z_O = 50 Ω, t_w = 1 μs, $t_r \le 10$ ns, $t_f \le 10$ ns.

Figure 3. Receiver Section Switching Test Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS

DRIVER
VOLTAGE TRANSFER CHARACTERISTICS

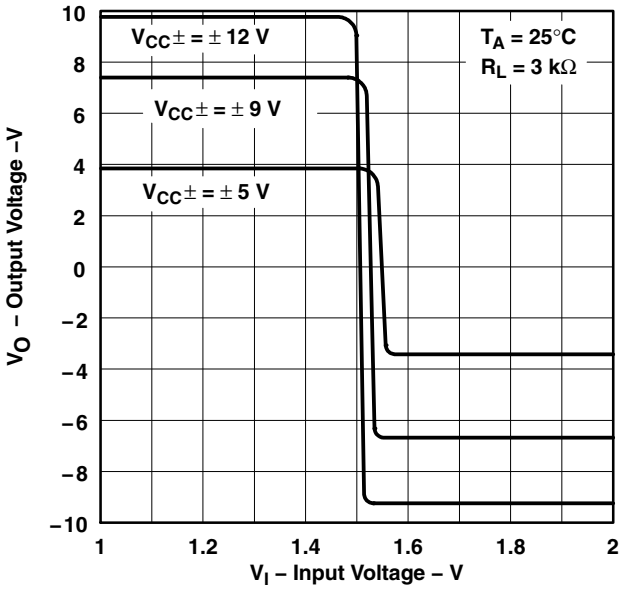


Figure 4

DRIVER
OUTPUT CURRENT
vs
OUTPUT VOLTAGE

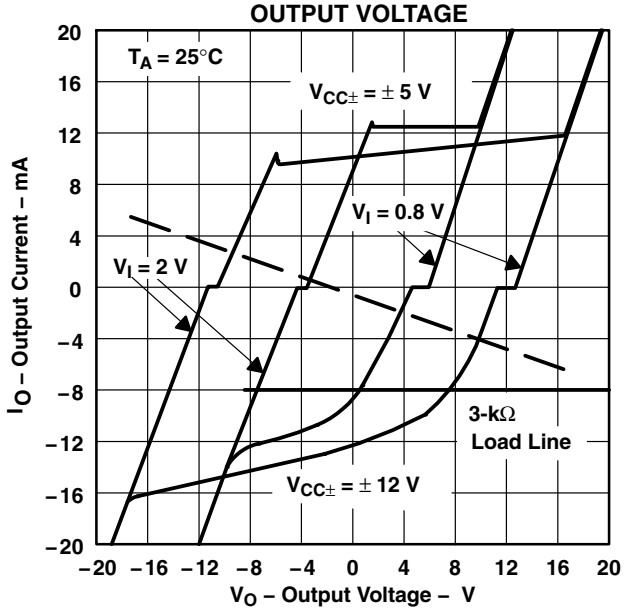


Figure 5

DRIVER
SHORT-CIRCUIT OUTPUT CURRENT
vs
FREE-AIR TEMPERATURE

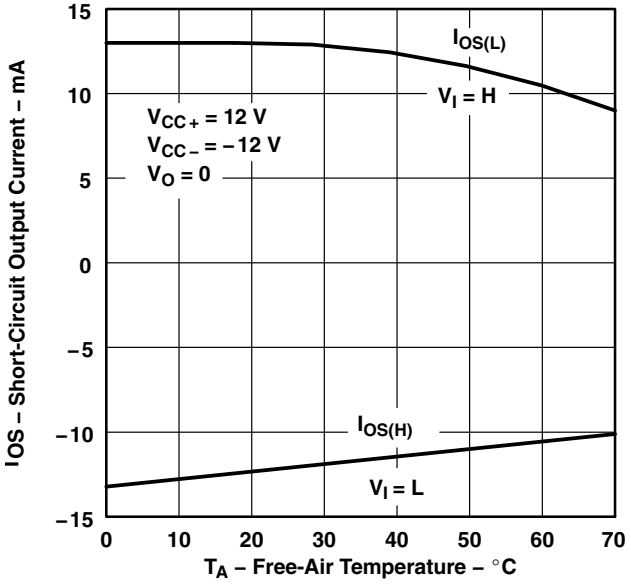


Figure 6

DRIVER
SLEW RATE
vs
LOAD CAPACITANCE

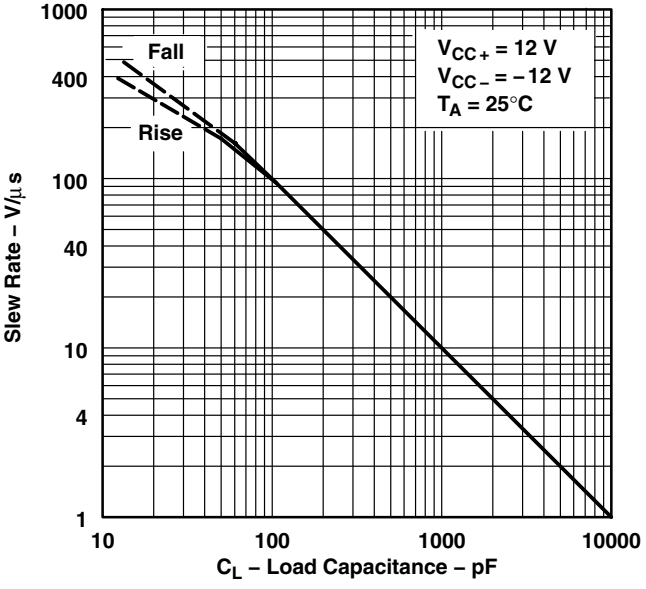


Figure 7

TYPICAL CHARACTERISTICS

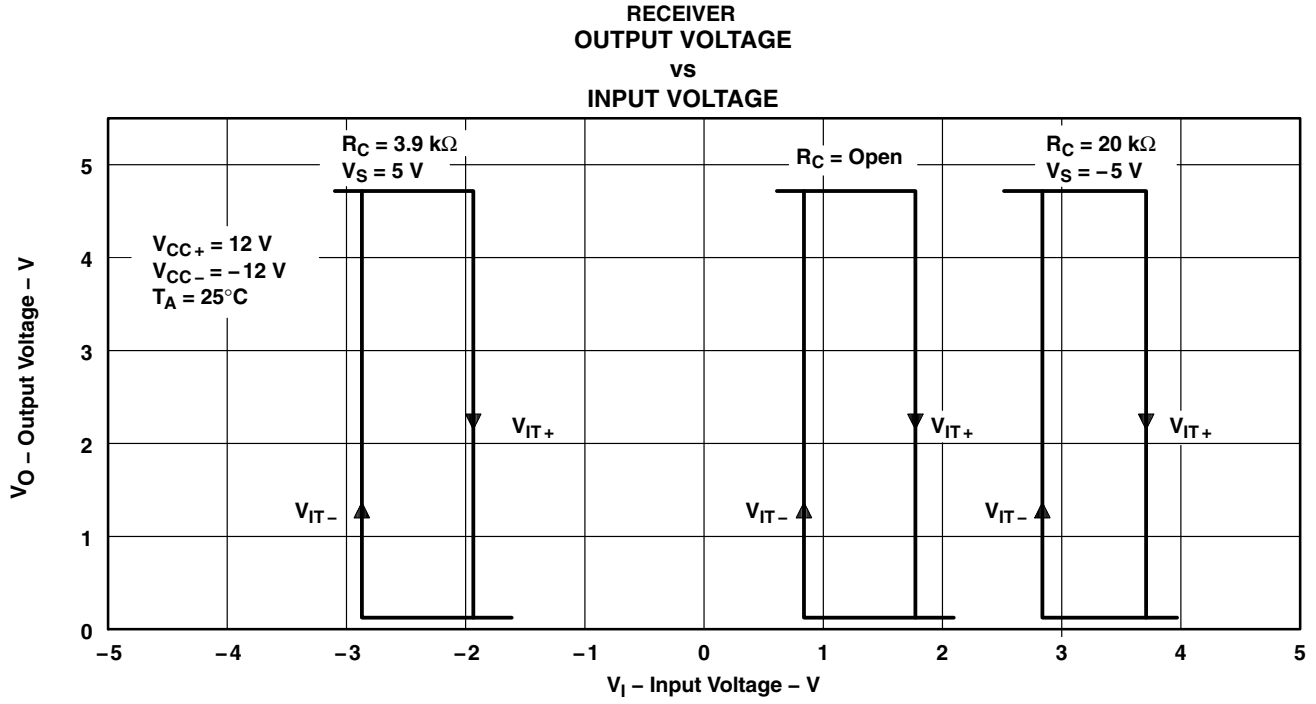


Figure 8

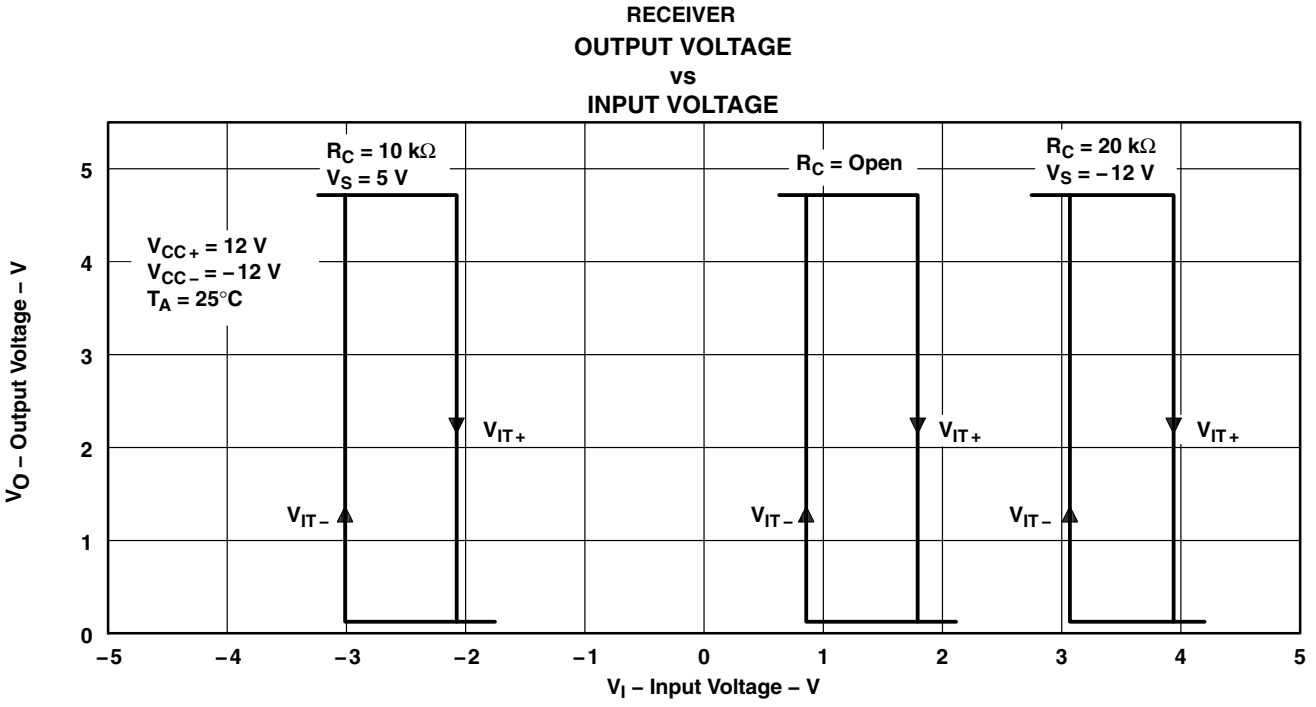


Figure 9

TYPICAL CHARACTERISTICS

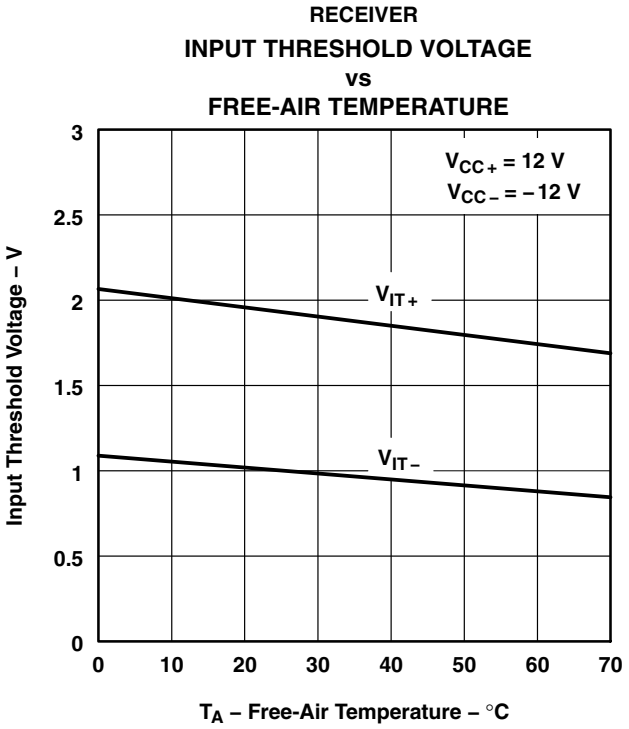


Figure 10

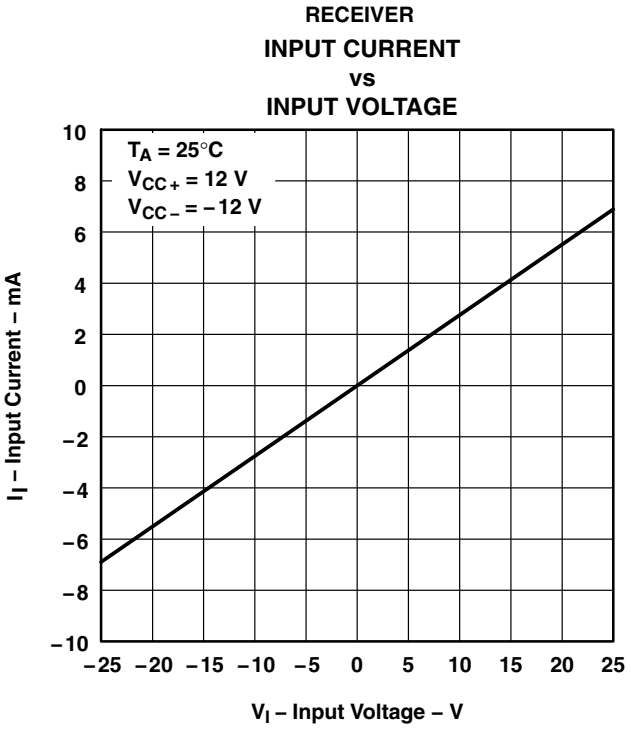


Figure 11

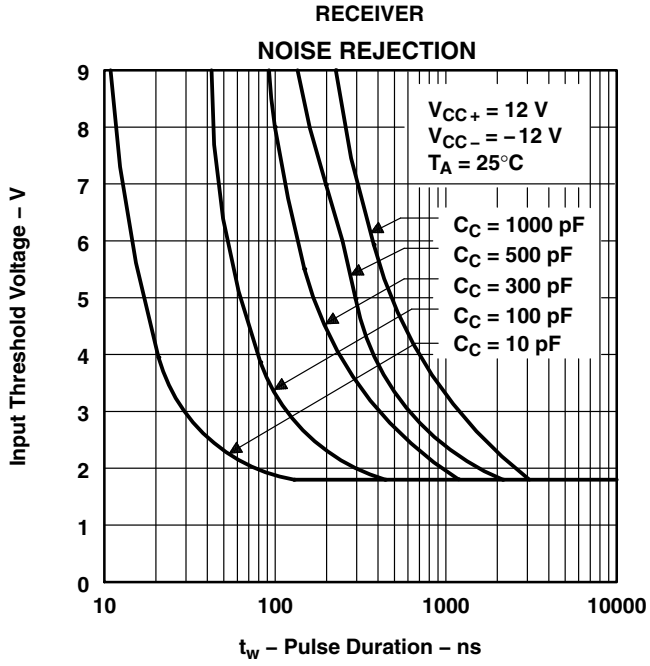


Figure 12

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN75155D	NRND	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	75155	
SN75155DR	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	75155	Samples
SN75155DRE4	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	75155	Samples
SN75155P	NRND	PDIP	P	8	50	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	SN75155P	

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

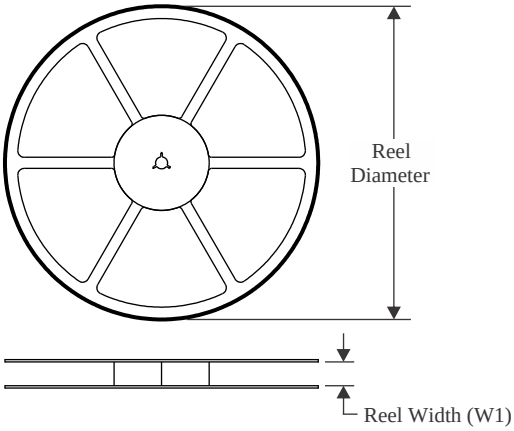
(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

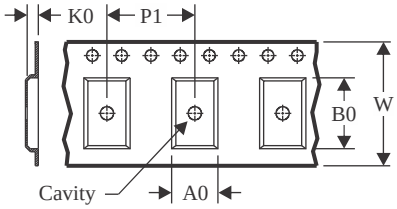
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

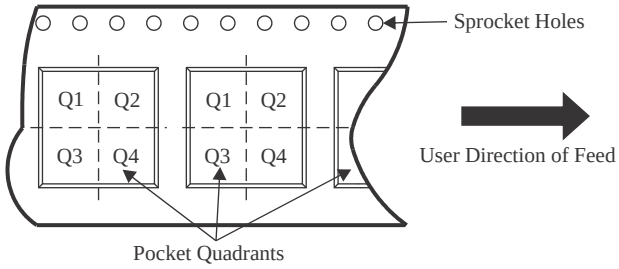


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

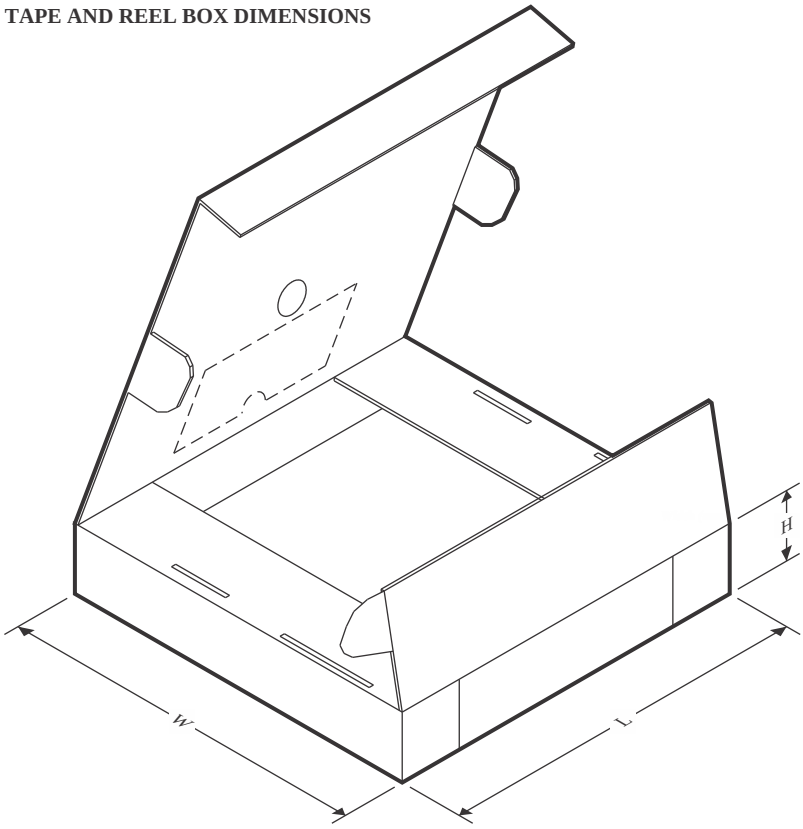
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75155DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

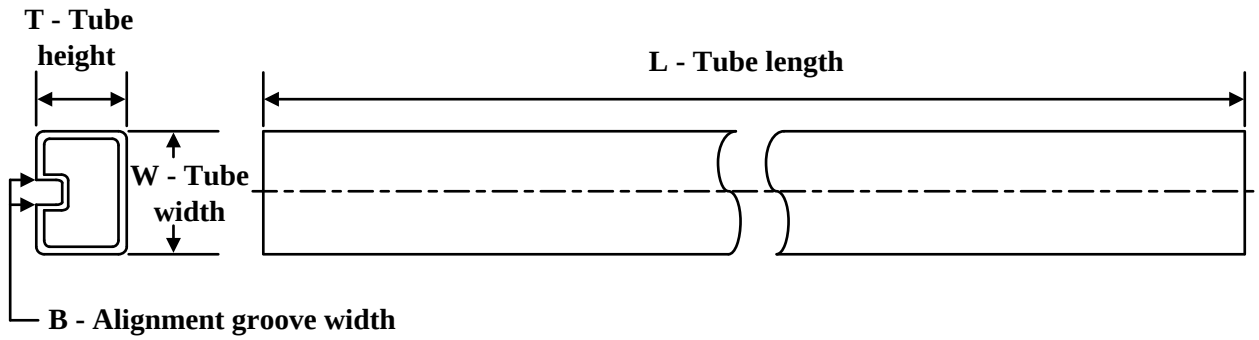
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

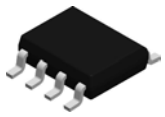
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75155DR	SOIC	D	8	2500	340.5	336.1	25.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN75155D	D	SOIC	8	75	507	8	3940	4.32
SN75155P	P	PDIP	8	50	506	13.97	11230	4.32

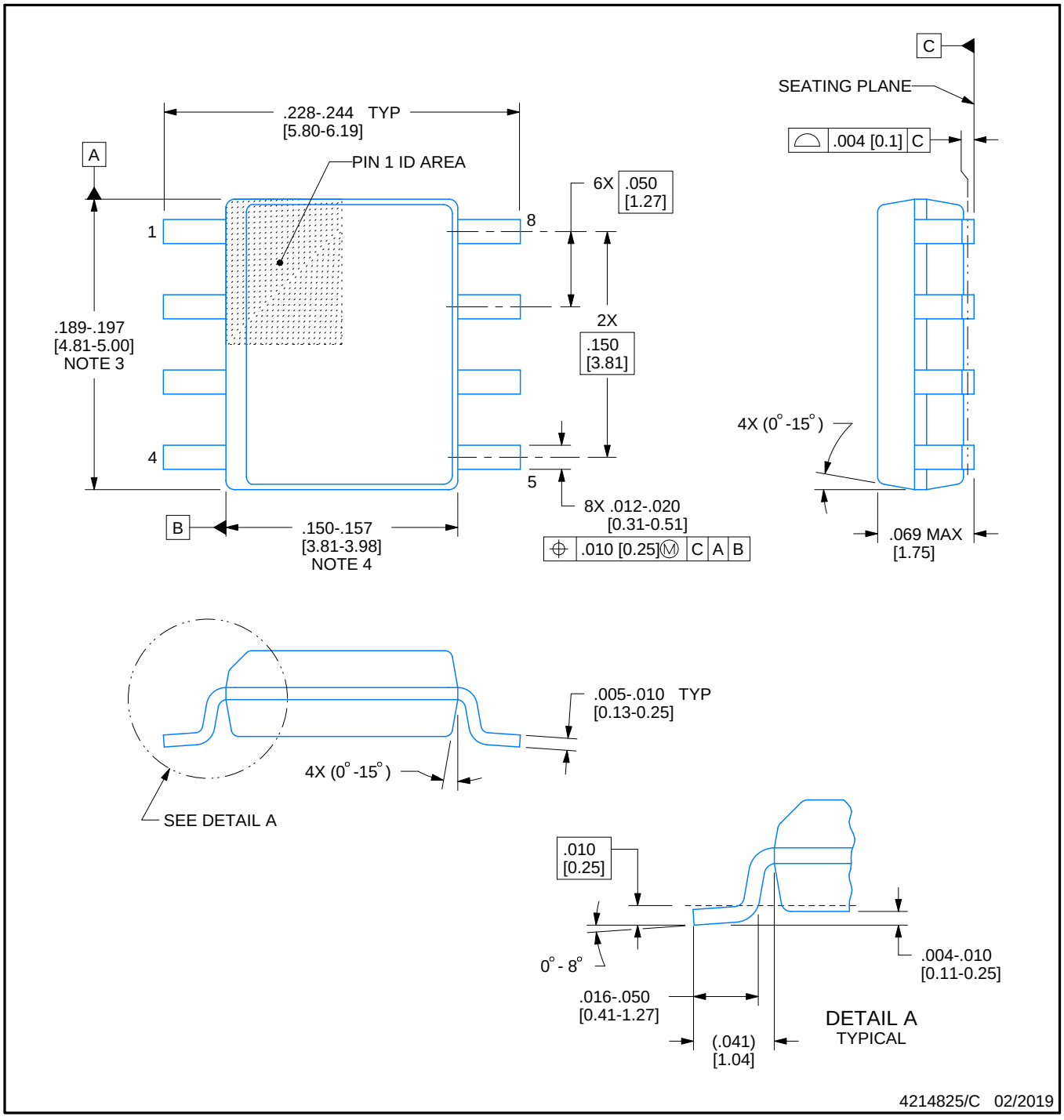


PACKAGE OUTLINE

D0008A

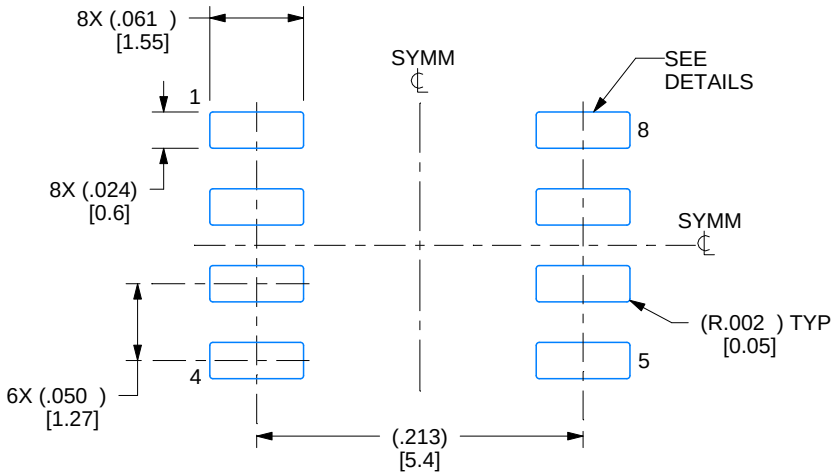
SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT

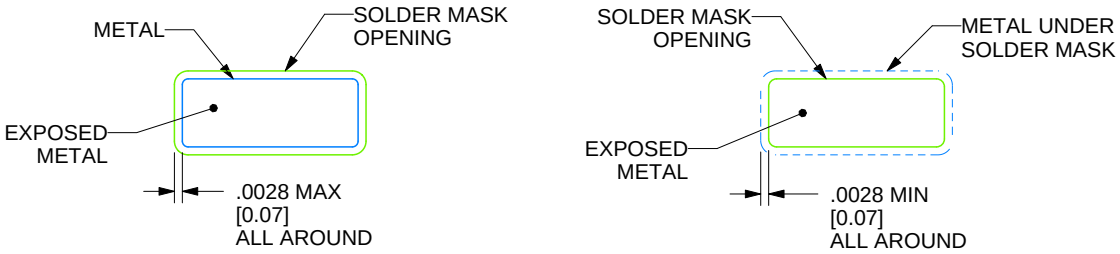


NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X



SOLDER MASK DETAILS

4214825/C 02/2019

NOTES: (continued)

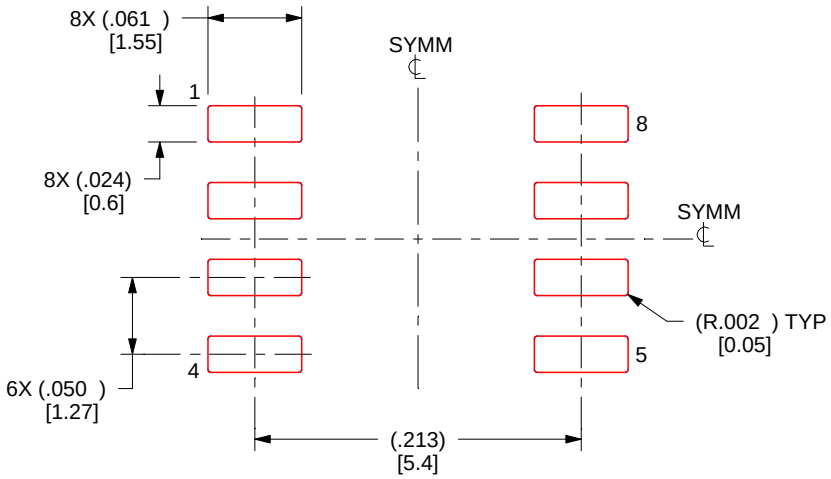
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



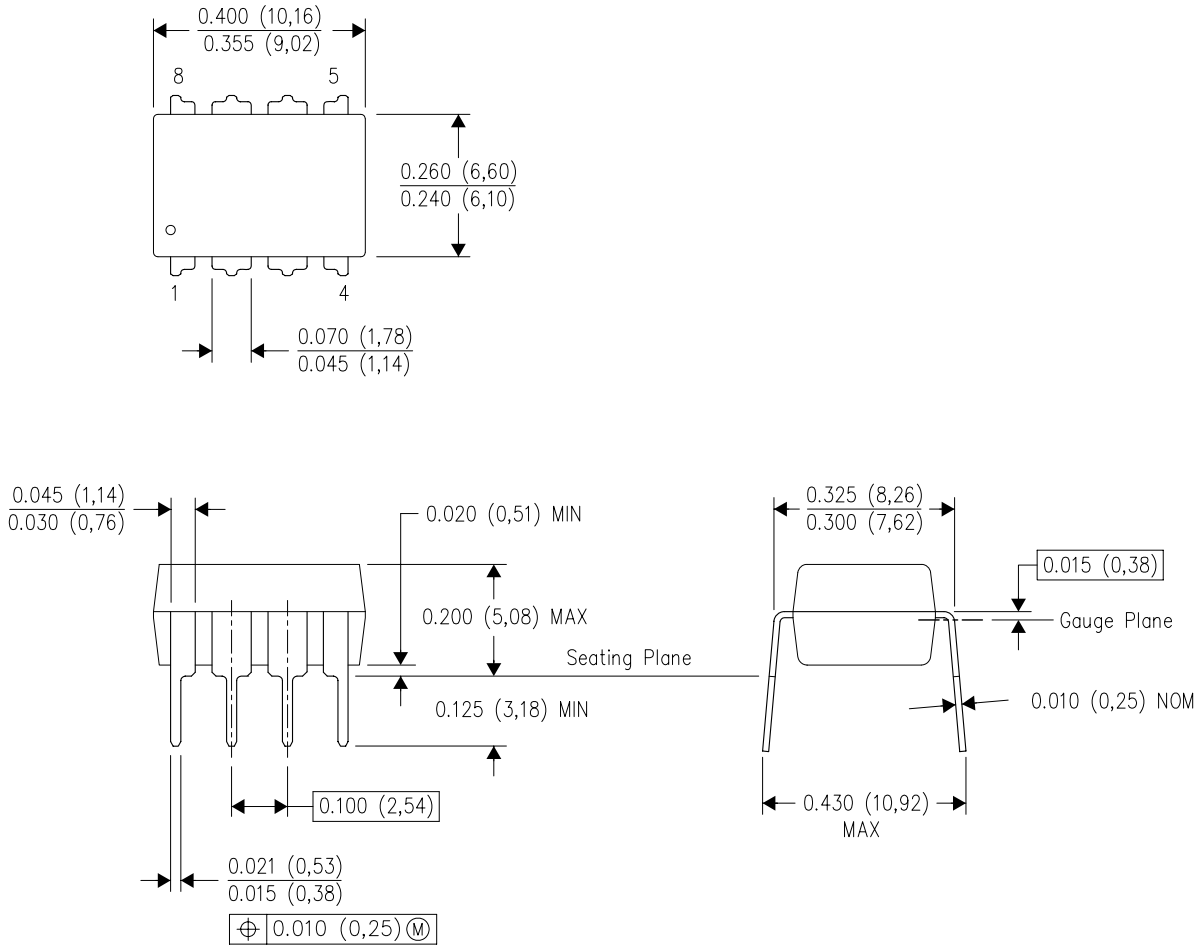
SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.125 MM] THICK STENCIL
SCALE:8X

4214825/C 02/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

P (R–PDIP–T8) PLASTIC DUAL–IN–LINE PACKAGE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001 variation BA.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES “AS IS” AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI’s products are provided subject to TI’s Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI’s provision of these resources does not expand or otherwise alter TI’s applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2024, Texas Instruments Incorporated